

06-01-2006

ASSIGN



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To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document or copy thereof.

113007 U.S. PTO
11/440163
052306

1. Names of conveying parties:
 - a) Sok Kiow Tan
 - b) Shenjian Liu
 - c) Harmeet Singh
 - d) Sam Do Lee
 - e) Linda Fung-Ming Lee
2. Name and address of receiving party:
 - a) Name: Lam Research Corporation
 - b) Address: 4650 Cushing Parkway Fremont, CA 94538

3. Nature of conveyance

<input checked="" type="checkbox"/>	Assignment	<input type="checkbox"/>	Merger
<input type="checkbox"/>	Security Agreement	<input type="checkbox"/>	Change of Name
<input type="checkbox"/>	Other _____	<input type="checkbox"/>	License Agreement

Execution Dates: a) May 17, 2006; b) May 16, 2006; c) May 17, 2006;
d) May 21, 2006; e) May 16, 2006

4. Application Number: Not yet assigned

The title of the new application is: TUNGSTEN SILICIDE ETCH PROCESS WITH
REDUCED ETCH RATE MICRO-LOADING

5. Please send all correspondence concerning this document to:

Lie-Yea Cheng, Agent
MARTINE PENILLA & GENCARELLA, LLP
710 Lakeway Drive, Suite 200
Sunnyvale, CA 94085
Tel. No. (408) 749-6900
Fax No.: (408) 749-6901
Customer No. 25920

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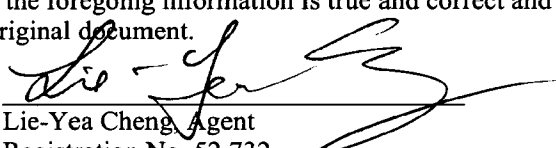
6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Enclosed
☐ Any deficiency is authorized to be charged to Deposit Account No. 50-0805
(Order No. LAM2P525)

8. To the best of my knowledge and belief, the foregoing information is true and correct and
any attached copy is a true copy of the original document.

Date: May 23, 2006


Lie-Yea Cheng, Agent
Registration No. 52,732

Attorney Docket No. LAM2P525/P1426

(Revised 01/96)

PATENT
REEL: 017938 FRAME: 0860

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

TUNGSTEN SILICIDE ETCH PROCESS WITH REDUCED ETCH RATE MICRO-LOADING

(Atty. Docket No. LAM2P525/P1426) for which we have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we the undersigned inventors hereby:

1) Sell, assign and transfer to Lam Research Corporation, a Delaware corporation having a place of business at 4650 Cushing Parkway Fremont, CA 94538 U.S. (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.

2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.

3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.

4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.

5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

1)	Signature: <u>Sok Kiow Tan</u>	Date: <u>5/17/06</u>
	Typed Name: Sok Kiow Tan	
2)	Signature: <u>Shenjian Liu</u>	Date: <u>5/16/06</u>
	Typed Name: Shenjian Liu	
3)	Signature: <u>Harmeet Singh</u>	Date: <u>5/17/2006</u>
	Typed Name: Harmeet Singh	
4)	Signature: _____	Date: _____
	Typed Name: Sam Do Lee	
5)	Signature: <u>Linda Fung-Ming Lee</u>	Date: <u>5/16/06</u>
	Typed Name: Linda Fung-Ming Lee	

Attorney Docket No. LAM2P525/P1426

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

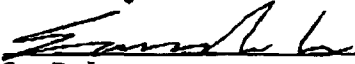
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- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

- | | | |
|----|--|---------------|
| 1) | Signature: _____
Typed Name: Sok Kiow Tan | Date: _____ |
| 2) | Signature: _____
Typed Name: Shenjian Liu | Date: _____ |
| 3) | Signature: _____
Typed Name: Harmeet Singh | Date: _____ |
| 4) | Signature: 
Typed Name: Sam Do Lee | Date: 5/21/06 |
| 5) | Signature: _____
Typed Name: Linda Fung-Ming Lee | Date: _____ |

Attorney Docket No. LAM2P525/P1426